

Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed
250°C/10 seconds at terminals

Mechanical Data

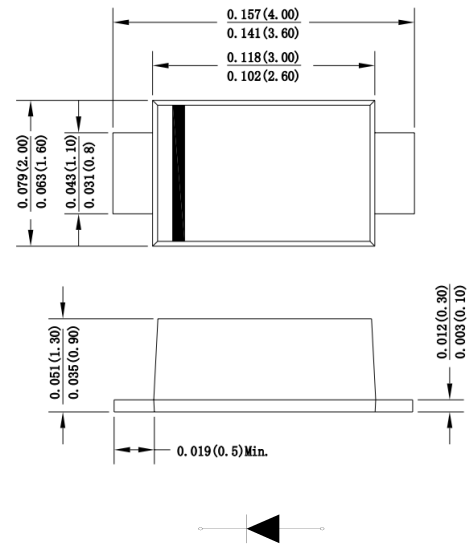
Case : Molded plastic body

Terminals : Solder plated, solderable per MIL-STD-750, Method 2026

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.0007 ounce, 0.02 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

| Parameter | SYMBOLS | A1 | A2 | A3 | A4 | A5 | A6 | A7 | UNITS |
|---|-----------------|-------------|-----|-----|-----|-----|-----|------|--------------------|
| Maximum repetitive peak reverse voltage | V_{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V_{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC blocking voltage | V_{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum average forward rectified current at $T_L=100^\circ\text{C}$ | $I_{(AV)}$ | 1.0 | | | | | | | A |
| Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load | I_{FSM} | 35.0 | | | | | | | A |
| Maximum instantaneous forward voltage at 1.0A | V_F | 1.10 | | | | | | | V |
| Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$ | I_R | 5.0 500 | | | | | | | μA |
| Typical junction capacitance (Note1) | C_J | 18.0 | | | | | | | pF |
| Typical thermal resistance | $R_{\theta JA}$ | 85.0 | | | | | | | $^\circ\text{C/W}$ |
| Operating junction and storage temperature range | T_J, T_{STG} | -55 to +150 | | | | | | | $^\circ\text{C}$ |

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

Ratings And Characteristic Curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

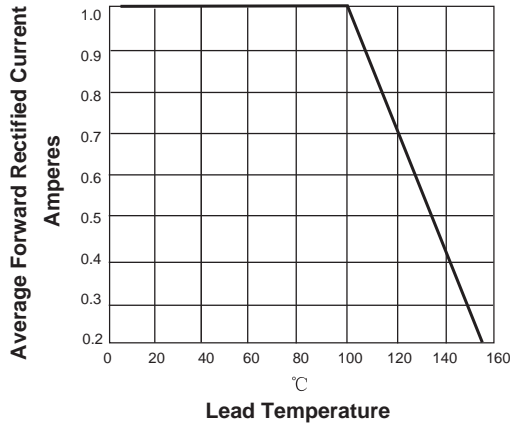


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

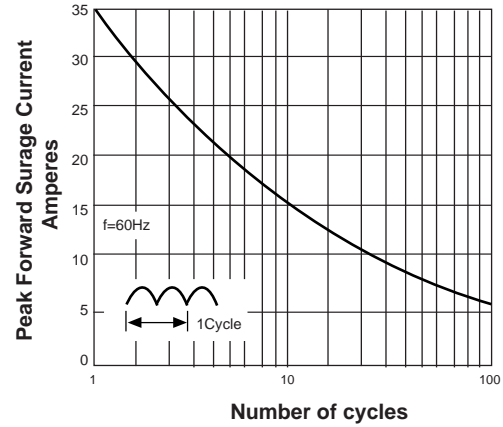


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

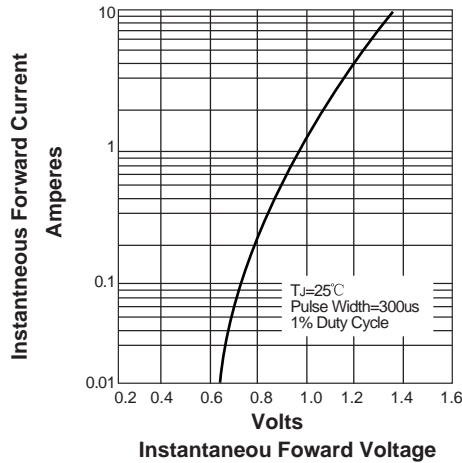
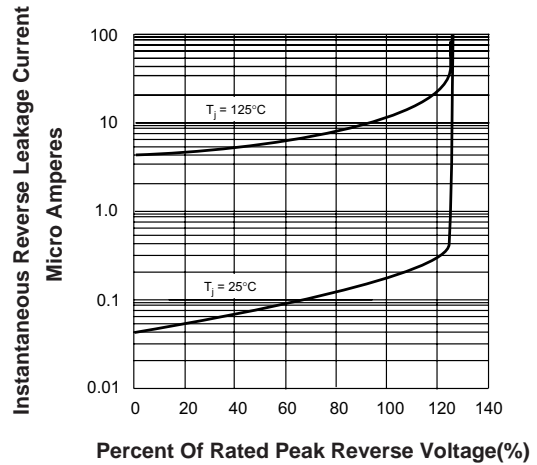
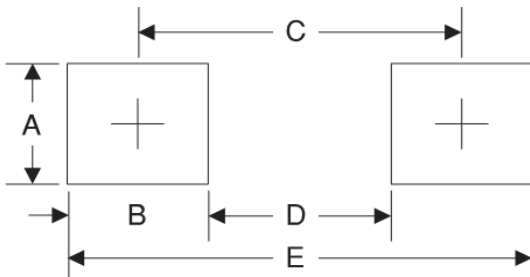


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

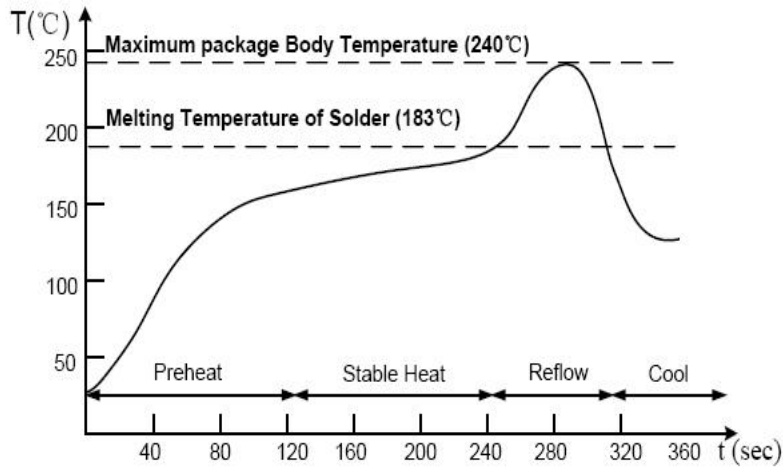


Suggested Pad Layout



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| A | 1.2 | 0.048 |
| B | 1.15 | 0.045 |
| C | 3.10 | 0.122 |
| D | 1.95 | 0.077 |
| E | 4.25 | 0.167 |

Suggested Soldering Temperature Profile

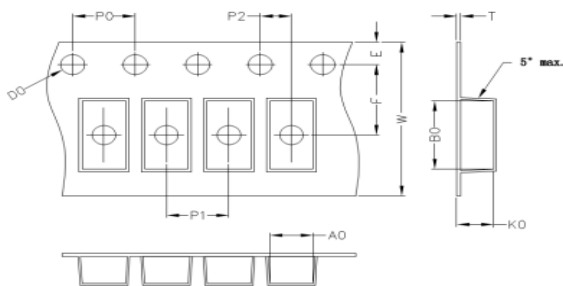


Note

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



| | | | | | |
|-----------|-----------|-----------|-----------|----------|------------------|
| A0 | B0 | K0 | D0 | E | F |
| 2.15 | 3.95 | 1.35 | 1.55 | 1.75 | 3.50 |
| P0 | P1 | P2 | T | W | Tolerance |
| 4.0 | 4.0 | 2.0 | 0.25 | 8 | 0.1 |

Package Specifications

| Package | Reel Size | Reel DIA. (mm) | Q'TY/Reel (Kpcs) | Box Size (mm) | QTY/Box (Kpcs) | Carton Size (mm) | Q'TY/Carton (Kpcs) |
|----------|-----------|----------------|------------------|---------------|----------------|------------------|--------------------|
| SOD123FL | 7' | 178 | 3 | 180 | 15 | 380*200*200 | 150 |